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Sommario/riassunto

The definitive resource for electroplating, now completely up to date With advances in information-age technologies, the field of electroplating has seen dramatic growth in the decade since the previous edition of Modern Electroplating was published. This expanded new edition addresses these developments, providing a comprehensive, one-stop reference to the latest methods and applications of electroplating of metals, alloys, semiconductors, and conductive polymers. With special emphasis on electroplating and electrochemical plating in nanotechnologies, data storage, and medical app
